

CTMLP080604BF

Series

From 0.24 μ H to 2.2 μ H



CHARACTERISTICS

Description: SMD Multi-layer Power Chip Inductor. Magnetically shielded.

Applications: Cellular phones, Power modules, DC/DC converters, Digital cameras, DVD, Portable devices, etc.

Operating Temperature: -55°C to 125°C (including self - temp. rise).

Isat: Inductance drop 30% from its value with current.

Irms: 40°C temperature rise from 25°C ambient with current.

Inductance Tolerance: $\pm 20\%$ (M), $\pm 30\%$ (N)

Packaging: Tape & Reel.

Miscellaneous: **RoHS Compliant.**

Additional Information: Additional electrical & physical information available upon request.

Samples available. See website for ordering information.

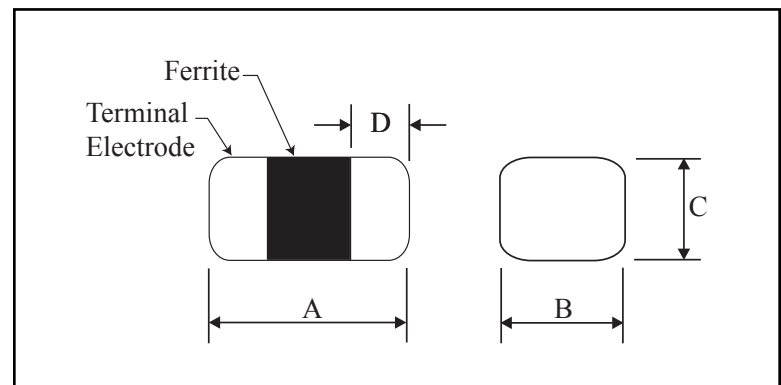
SPECIFICATIONS

Please specify tolerance code when ordering.
CTMLP080604BF-R47_ ← M = $\pm 20\%$, N = $\pm 30\%$

Part Number	Inductance (μ H)	Test Frequency	DCR $\pm 25\%$ (Ω)	Isat Max.(Typ.) (mA)	Irms Max.(Typ.) (mA)
CTMLP080604BF-R24_	0.24	3.0MHz, 200mV	0.023	3600(4000)	3500(4200)
CTMLP080604BF-R47_	0.47	3.0MHz, 200mV	0.037	2500(2900)	2600(3100)
CTMLP080604BF-R68_	0.68	3.0MHz, 200mV	0.065	2500(2800)	2400(2800)
CTMLP080604BF-1R0_	1.0	3.0MHz, 200mV	0.068	1500(1900)	2200(2600)
CTMLP080604BF-1R5_	1.5	3.0MHz, 200mV	0.100	1500(1800)	1600(1900)
CTMLP080604BF-2R2_	2.2	3.0MHz, 200mV	0.210	1000(1300)	1500(1800)

PHYSICAL DIMENSIONS

Size	A	B	C Max.	D
mm	2.0 \pm 0.20	1.6 \pm 0.20	1.00	0.5 \pm 0.3
inches	0.079 \pm 0.008	0.063 \pm 0.008	0.039	0.020 \pm 0.012



PAD LAYOUT

